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## **Ultratech Receives Follow-On Multiple Orders From China Foundries For Laser Spike Annealing Systems**

### **Demand Grows for Ultratech's LSA101 Dual-Beam Systems from China Foundries' Volume Production**

SAN JOSE, Calif., March 21, 2017 /PRNewswire/ -- Ultratech, Inc. (Nasdaq: UTEK), a leading supplier of lithography, laser-processing and inspection systems used to manufacture semiconductor devices and high-brightness LEDs (HB-LEDs), as well as atomic layer deposition (ALD) systems, today announced that two China foundries placed follow-on orders for laser spike anneal systems. Ultratech's LSA101 laser spike anneal systems will be used for 40- and 28-nm production. The LSA101 dual-beam tools were chosen over competing systems due to greater flexibility and capability for annealing with low overall thermal budgets. Ultratech plans to ship the LSA101 tools to the customers' foundries to China in Q1 2017.

The low cost of 28-nm planar technology continues to drive growth and numerous foundries are ramping capacity expansion to take advantage of the optimal performance-to-cost ratio at this geometry. Foundries in Asia are leveraging the value proposition offered at the 28-nm node to meet the strong demand for low-cost chips for mobile devices. The LSA101 dual-beam system is designed for advanced applications, such as gate stack formation, silicide or post-silicide anneal to deliver leading technology in a cost-effective solution. Cost-driven foundries value Ultratech's LSA101 systems due to the impressive flexibility to meet requirements for today's volume production at 40-nm, 28-nm, and extendibility to 14-nm, 10-nm and below nodes.

"These follow-on orders strengthen our dominant position for advanced millisecond anneal within the foundry market in China," said Jim McWhirter, Ph.D., vice president and senior scientist, laser technology at Ultratech. "While we are currently working with these customers to ramp capacity for 40- and 28-nms, the LSA101 system has demonstrated extendibility for advanced FinFET nodes. As a result, building on our long-term relationships, we can effectively work with our customers using our LSA systems to support their planer device applications today with extendibility for their future FinFET device roadmaps. Ultratech's product focus remains targeted at meeting customer requirements for their advanced millisecond annealing applications."

#### **Ultratech LSA 101 Dual-Beam Laser Spike Anneal System**

Built on the customizable Unity Platform™, LSA101 with the dual-beam option expands the process space by adding a second low-power laser beam that adds process flexibility and enables millisecond annealing with a low thermal budget process. Inserting a millisecond anneal step post-junction formation, such as gate stack formation, silicide or post-silicide anneal, has been shown to improve leakage and device reliability, while reducing contact resistance and improving both performance and yield. Compared to competing millisecond annealing technologies, LSA with dual-beam offers the lowest thermal budget millisecond anneal process along with superior within-die uniformity for different layouts. The LSA101 delivers high flexibility and extendibility for advanced annealing applications and is currently in high-volume production for planer and FinFET logic devices.

#### **Safe Harbor**

This release includes forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Forward-looking statements can generally be identified by words such as "anticipates," "expects," "remains," "thinks," "intends," "believes," "estimates," and similar expressions and include management's current expectation of its longer term prospects for success. These forward-looking statements are based on our current expectations, estimates, assumptions and projections about our business and industry, and the markets and customers we serve, and they are subject to numerous risks and uncertainties that may cause these forward-looking statements to be inaccurate. Such risks and uncertainties include the timing and possible delays, deferrals and cancellations of orders by customers; quarterly revenue fluctuations; industry and sector cyclicality, instability and unpredictability; market demand for consumer devices utilizing semiconductors produced by our clients; our ability to manage costs; new product introductions, market acceptance of new products and enhanced versions of our existing products; reliability and technical acceptance of our products; our lengthy sales cycles, and the timing of system installations and acceptances; lengthy and costly development cycles for laser-processing and lithography technologies and applications; competition and consolidation in the markets we serve; improvements, including in cost and technical features, of competitors' products; rapid technological change; pricing pressures and product discounts; our ability to collect receivables; customer and product concentration and lack of product revenue diversification; inventory obsolescence; general economic, financial market and political conditions and other factors outside of our control; domestic and international tax policies; cybersecurity threats in the United States and globally that could impact our industry, customers, and technologies; and other factors described in our SEC reports including our Annual Report on Form 10-K filed for the year ended December 31, 2016. Due to these and other factors, the statements,

historical results and percentage relationships set forth herein are not necessarily indicative of the results of operations for any future period. We undertake no obligation to revise or update any forward looking statements to reflect any event or circumstance that may arise after the date of this release.

**About Ultratech:** Ultratech, Inc. (Nasdaq: UTEK) designs, builds and markets manufacturing systems for the global technology industry. Founded in 1979, Ultratech serves three core markets: frontend semiconductor, backend semiconductor, and nanotechnology. The company is the leading supplier of lithography products for bump packaging of integrated circuits and high brightness LEDs. Ultratech is also the market leader and pioneer of laser spike anneal technology for the production of advanced semiconductor devices. In addition, the company offers solutions leveraging its proprietary coherent gradient sensing (CGS) technology to the semiconductor wafer inspection market and provides atomic layer deposition (ALD) tools to leading research organizations, including academic and industrial institutions. Visit Ultratech online at: [www.ultratech.com](http://www.ultratech.com).  
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